

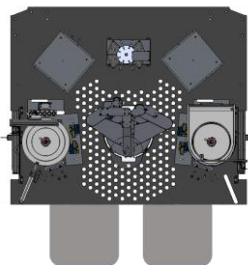
# HIGHLY FLEXIBLE WAFER PROCESSING

Our modular **amcoss amc 3000** spinner is the perfect completion of our **amc** series of fully automatic single wafer processing tools. With its substrate-size-range between 150 and 300 mm (9" square) **amc 3000** offers very flexible applications in coating, lift-off, developing, cleaning, vapor priming and heating of wafers and masks. As always, we focus on our customers' needs and therefore, every tool may be optimized for either flexible single processes or high throughput. The possibility of FOUP loading via robot or rail system in the cleanroom or plant is just as self-evident as the integration of an optional 300 mm SECS.

**amc300 - fully automatic single wafer processing equipment ready for robot FOUP loading**



**amc**  
**3000**



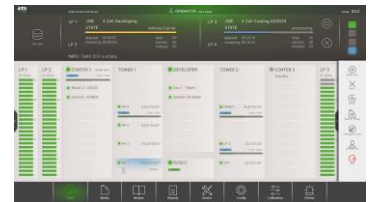
## Beneficial highlights

**300 mm SECS/GEM interface:** our **ams PILOT** software is configured to support 300 mm standard SECS/GEM communication or other customized protocols if needed.

**Proven amc key features:** **amc3000** stands out due to all proven technical features of the other **amc** models, as well as the unique user-friendly machine design. A **genuine** through-the-wall installation is possible, just as are flexible machine adjustments and easy maintenance.

**Safe:** the equipment is designed accordingly to the newest safety rules.

**Full process control:** each selected process is managed by the relevant module of our comfortable **amcoss amc PILOT** software complying with Semi-Standard E95-1101. All necessary parameters can be adjusted and will be logged into the software.



**Unique single-nozzle grip:** The innovative positioning arm with single-nozzle grip carries only one nozzle at the time. This avoids particle build-up caused by friction of rubbing tubes. All nozzles momentarily not required, remain within the nozzle storage with rinse and drip pan, which prevent the tip of the nozzle from drying out and impede delayed dripping onto the substrate.

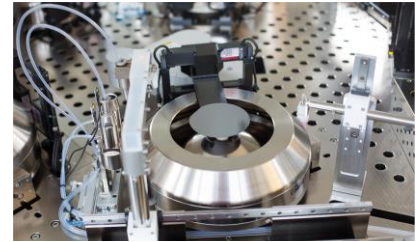


- // Wafer diameters: 150 mm up to 300 mm or 7" x 7" up to 9" x 9"
- // Up to 2 I/O stations for 150 mm to 200 mm open cassettes or 300 mm FOUP
- // Max. 5 individual processing modules
- // 1 two-link robot handler with single or double end-effector
- // Outer dimensions: 1596 mm x 2082 mm

## Modular system for customer-specific equipment

### amc coater module

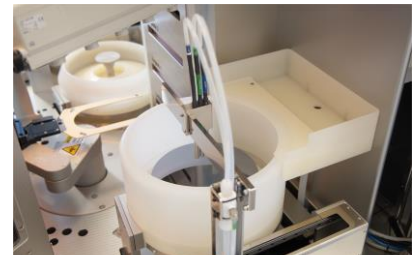
- // Unique bowl design for optimal process results (e.g. no cotton candy when processing high viscosity resists)
- // Servo-controlled nozzle positioning, programmable with absolute distance values
- // Programmable wafer backside and bowl rinse
- // EBR (Edge Bead Removal) system programmable with absolute distance values, also for rectangular substrates
- // Dispense system for up to 6 different media per bowl with single-nozzle positioning arm and automatic nozzle change
- // Different resists dispense pumps (e.g. syringe, traptank, etc.) available



Coater module with servo-controlled single-nozzle positioning arm, EBR, and exhaust

### amc developer module

- // Spray-, puddle or megasonic development
- // Various developer media per bowl possible
- // Servo-controlled nozzle positioning programmable with absolute distance values
- // Programmable wafer backside, topside and bowl rinse



Developer module with high splash ring for spray and puddle developing.

### amc lift-off module

- // Unique lift-off process with large-area megasonic
- // High- or medium-pressure cleaning with DIW or solvents
- // Special reclaim solution for minimal media consumption
- // Easy recycling of lifted metals
- // Programmable wafer backside, topside and bowl rinse

### amc etching module

- // Etching of a multitude of round and square wafers and masks
- // Precise media tempering solution and control
- // Novel chrome etchant recycling reduces use of chemicals and thus, reduces the impact on the environment and decreases processing costs

### amc cleaning module

- // Cleaning of wafer frontside, backside and edge bevel
- // Various cleaning methods as standard solutions available
- // Large area megasonic



Solvent module for lift-off or resist strip for standard solvents and various lift-off techniques

### amc temperature module

- // Up to 5 (optional 6) hot- or coolplates per module
- // Standard hotplate (60 °C – 200 °C)
- // High-temperature hotplate (60 °C – 450 °C)
- // HMDS vapor priming hotplate (60 °C – 200 °C)
- // Single or multi-zone hotplate
- // Coolplate (10 °C – 60 °C), with either water or Peltier cooling
- // Curing by UV light or supported by UV light
- // Options for proximity control: Fixed proximity, programmable proximity, vacuum contact

### amc wafer-handling module

- // „Pick and place“ robot
- // Contactless wafer centring „on-the-fly“
- // Slot-scanning including identification of carrier type and wafer size
- // OCR, bar- and matrix-code support
- // Wafer vacuum or edge gripping

### Optional configurations

- // Thin wafer processing
- // Backside coating with automatic flip station
- // Perforated wafer processing
- // Mini environment with temperature and humidity control
- // Resist and developer temperature control
- // Media tempering device to the point of use

